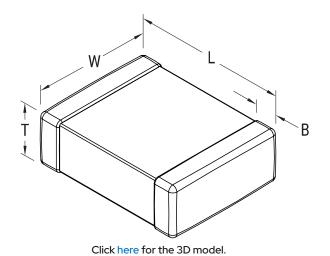


CBR02C669B3GAC

General Information

CBR-SMD RF COG, Ceramic, 6.6 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



CBR-SMD RF COG Series Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 0.3 mg Notes Solder Reflow Only. Shelf Life 78 Weeks MSL 1

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

15000

T&R, 180mm, Plastic Tape

Packaging Specifications	
Packaging	

Packaging Quantity

Specifications	
Capacitance	6.6 pF
Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.188%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	532

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